



PH9130AL

N-channel 9.1 mΩ 30 V TrenchMOS logic level FET in LPAK

Rev. 5 — 14 January 2011

Product data sheet

1. Product profile

1.1 General description

Logic level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product is designed and qualified for use in computing and consumer applications.

1.2 Features and benefits

- High efficiency due to low switching and conduction losses
- Suitable for logic level gate drive sources

1.3 Applications

- Consumer applications
- Desktop Voltage Regulator Module (VRM)
- Notebook Voltage Regulator Module (VRM)

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25\text{ °C}; T_j \leq 175\text{ °C}$	-	-	30	V
I_D	drain current	$T_{mb} = 25\text{ °C}; V_{GS} = 10\text{ V};$ see Figure 1	-	-	57	A
P_{tot}	total power dissipation	$T_{mb} = 25\text{ °C};$ see Figure 2	-	-	52	W
Static characteristics						
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}; I_D = 15\text{ A};$ $T_j = 25\text{ °C}$	-	7.8	9.1	mΩ
Dynamic characteristics						
Q_{GD}	gate-drain charge	$V_{GS} = 10\text{ V}; I_D = 30\text{ A};$ $V_{DS} = 15\text{ V};$ see Figure 14 ; see Figure 15	-	2.6	-	nC

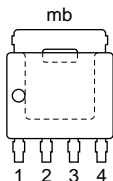
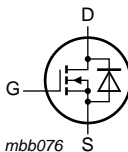


Table 1. Quick reference data ...continued

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$Q_{G(\text{tot})}$	total gate charge	$V_{GS} = 4.5 \text{ V}$; $I_D = 30 \text{ A}$; $V_{DS} = 15 \text{ V}$; see Figure 14	-	9	-	nC
Avalanche ruggedness						
$E_{DS(\text{AL})S}$	non-repetitive drain-source avalanche energy	$V_{GS} = 10 \text{ V}$; $T_{j(\text{init})} = 25 \text{ }^\circ\text{C}$; $I_D = 57 \text{ A}$; $V_{\text{sup}} \leq 30 \text{ V}$; $R_{GS} = 50 \text{ } \Omega$; unclamped	-	-	17	mJ

2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source		
2	S	source		
3	S	source		
4	G	gate		
mb	D	mounting base; connected to drain		

SOT669 (LPAK)

3. Ordering information

Table 3. Ordering information

Type number	Package		Version
	Name	Description	
PH9130AL	LPAK	plastic single-ended surface-mounted package (LPAK); 4 leads	SOT669

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{DS}	drain-source voltage	T _j ≥ 25 °C; T _j ≤ 175 °C	-	30	V
V _{DSM}	peak drain-source voltage	t _p ≤ 25 ns; f ≤ 500 kHz; E _{DS(AL)S} ≤ 60 nJ; pulsed	-	35	V
V _{DGR}	drain-gate voltage	T _j ≥ 25 °C; T _j ≤ 175 °C; R _{GS} = 20 kΩ	-	30	V
V _{GS}	gate-source voltage		-20	20	V
I _D	drain current	V _{GS} = 10 V; T _{mb} = 100 °C; see Figure 1	-	40	A
		V _{GS} = 10 V; T _{mb} = 25 °C; see Figure 1	-	57	A
I _{DM}	peak drain current	pulsed; t _p ≤ 10 μs; T _{mb} = 25 °C; see Figure 3	-	229	A
P _{tot}	total power dissipation	T _{mb} = 25 °C; see Figure 2	-	52	W
T _{stg}	storage temperature		-55	175	°C
T _j	junction temperature		-55	175	°C
Source-drain diode					
I _S	source current	T _{mb} = 25 °C	-	57	A
I _{SM}	peak source current	pulsed; t _p ≤ 10 μs; T _{mb} = 25 °C	-	229	A
Avalanche ruggedness					
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	V _{GS} = 10 V; T _{j(initial)} = 25 °C; I _D = 57 A; V _{sup} ≤ 30 V; R _{GS} = 50 Ω; unclamped	-	17	mJ

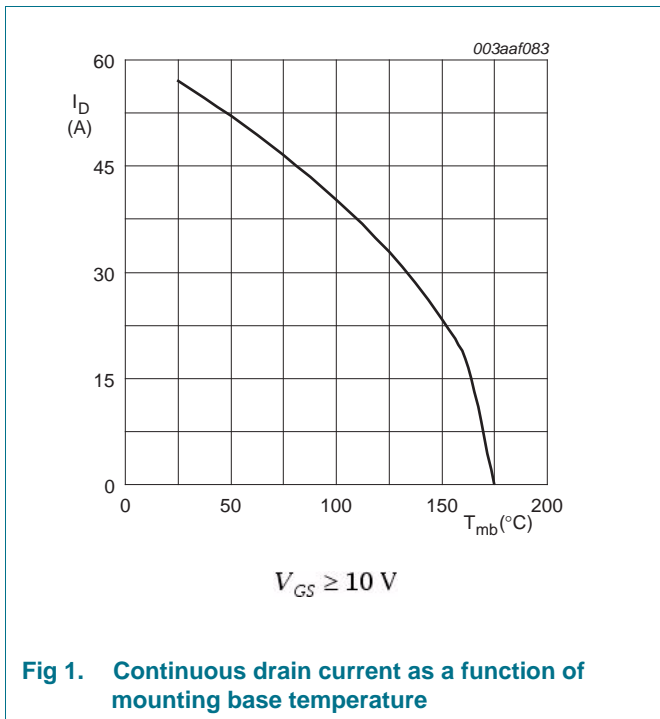


Fig 1. Continuous drain current as a function of mounting base temperature

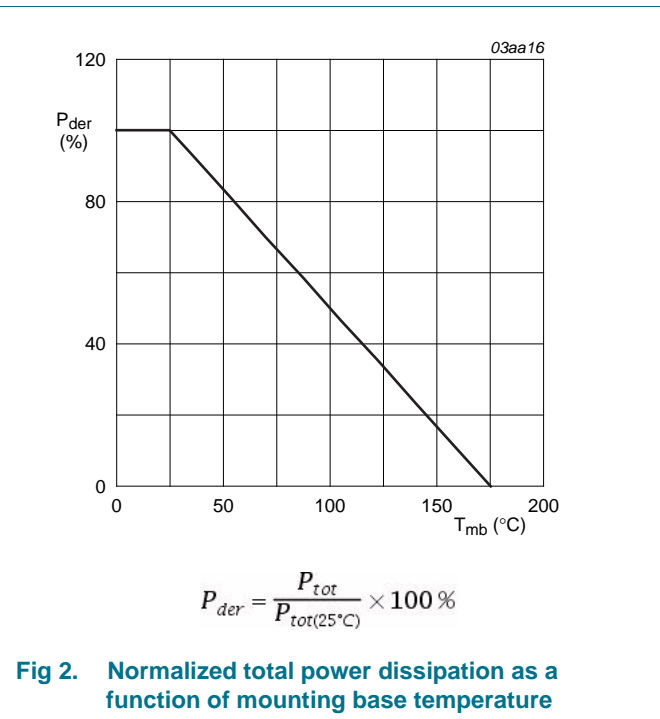
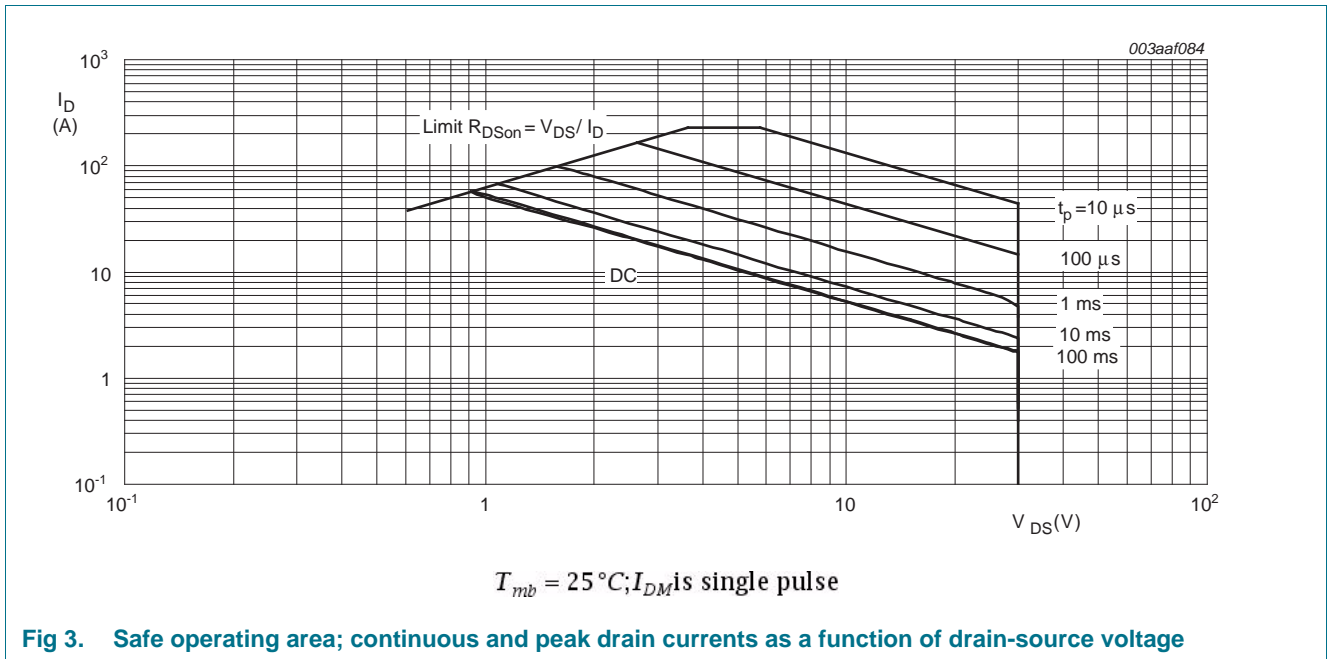


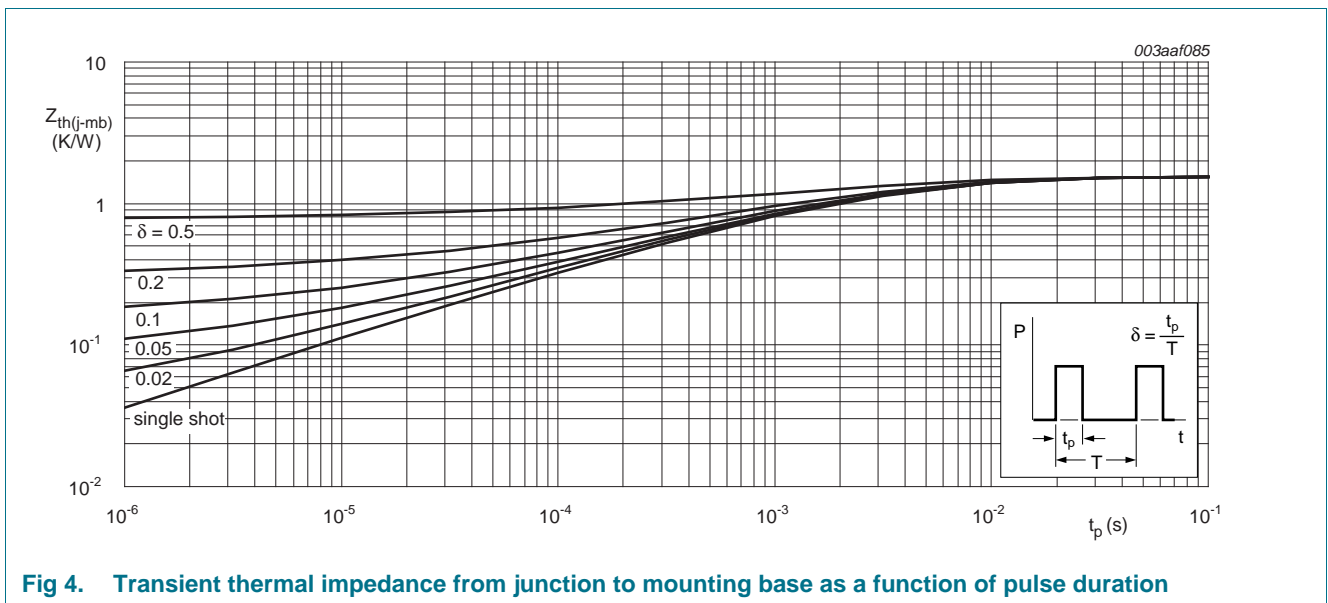
Fig 2. Normalized total power dissipation as a function of mounting base temperature



5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	see Figure 4	-	1.54	2.87	K/W



6. Characteristics

Table 6. Characteristics
Tested to JEDEC standards where applicable.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu\text{A}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	30	-	-	V
		$I_D = 250 \mu\text{A}; V_{GS} = 0 \text{ V}; T_j = -55 \text{ }^\circ\text{C}$	27	-	-	V
		$I_D = 18 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}; t_p = 50 \mu\text{s}$	32.5	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ }^\circ\text{C};$ see Figure 11 ; see Figure 12	1.3	1.7	2.15	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 150 \text{ }^\circ\text{C};$ see Figure 12	0.5	-	-	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ }^\circ\text{C};$ see Figure 12	-	-	2.55	V
I_{DSS}	drain leakage current	$V_{DS} = 30 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	0.02	1	μA
		$V_{DS} = 30 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 150 \text{ }^\circ\text{C}$	-	-	100	μA
I_{GSS}	gate leakage current	$V_{GS} = 16 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	10	100	nA
		$V_{GS} = -16 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	10	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 4.5 \text{ V}; I_D = 15 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$	-	-	13.6	mΩ
		$V_{GS} = 10 \text{ V}; I_D = 15 \text{ A}; T_j = 150 \text{ }^\circ\text{C};$ see Figure 13	-	-	16.4	mΩ
		$V_{GS} = 10 \text{ V}; I_D = 15 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$	-	7.8	9.1	mΩ
R_G	gate resistance	$f = 1 \text{ MHz}$	-	2.03	-	Ω
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	$I_D = 30 \text{ A}; V_{DS} = 15 \text{ V}; V_{GS} = 4.5 \text{ V};$ see Figure 14	-	9	-	nC
		$I_D = 30 \text{ A}; V_{DS} = 15 \text{ V}; V_{GS} = 10 \text{ V};$ see Figure 14 ; see Figure 15	-	18	-	nC
		$I_D = 0 \text{ A}; V_{DS} = 0 \text{ V}; V_{GS} = 10 \text{ V}$	-	16	-	nC
Q_{GS}	gate-source charge	$I_D = 30 \text{ A}; V_{DS} = 15 \text{ V}; V_{GS} = 10 \text{ V};$ see Figure 14 ; see Figure 15	-	4	-	nC
$Q_{GS(th)}$	pre-threshold gate-source charge		-	1.7	-	nC
$Q_{GS(th-pl)}$	post-threshold gate-source charge		-	2.3	-	nC
Q_{GD}	gate-drain charge		-	2.6	-	nC
$V_{GS(pl)}$	gate-source plateau voltage	$V_{DS} = 15 \text{ V};$ see Figure 14 ; see Figure 15	-	3.2	-	V
C_{iss}	input capacitance	$V_{DS} = 15 \text{ V}; V_{GS} = 0 \text{ V}; f = 1 \text{ MHz};$ $T_j = 25 \text{ }^\circ\text{C};$ see Figure 16	-	894	-	pF
C_{oss}	output capacitance		-	182	-	pF
C_{rss}	reverse transfer capacitance		-	98	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 15 \text{ V}; R_L = 1.5 \text{ } \Omega; V_{GS} = 4.5 \text{ V};$ $R_{G(ext)} = 4.7 \text{ } \Omega$	-	14	-	ns
t_r	rise time		-	20	-	ns
$t_{d(off)}$	turn-off delay time		-	18	-	ns

Table 6. Characteristics ...continued
 Tested to JEDEC standards where applicable.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_f	fall time	$V_{DS} = 15\text{ V}$; $R_L = 0.5\ \Omega$; $V_{GS} = 4.5\text{ V}$; $R_{G(ext)} = 4.7\ \Omega$	-	7	-	ns
Source-drain diode						
V_{SD}	source-drain voltage	$I_S = 25\text{ A}$; $V_{GS} = 0\text{ V}$; $T_j = 25\text{ }^\circ\text{C}$; see Figure 17	-	0.9	1.2	V
t_{rr}	reverse recovery time	$I_S = 10\text{ A}$; $di_S/dt = -100\text{ A}/\mu\text{s}$; $V_{GS} = 0\text{ V}$;	-	13	-	ns
Q_r	recovered charge	$V_{DS} = 15\text{ V}$	-	25	-	nC

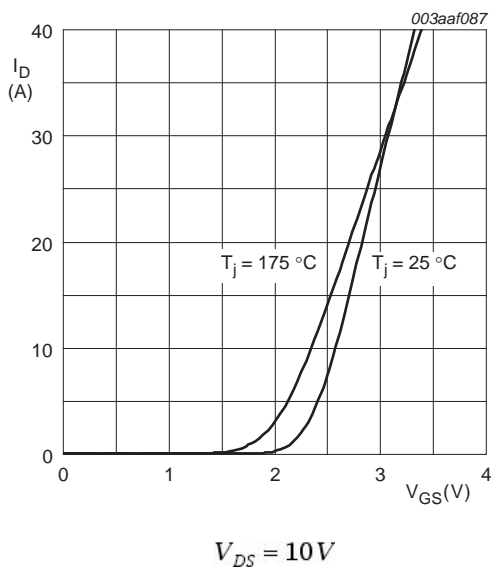


Fig 5. Transfer characteristics: drain current as a function of gate-source voltage; typical values

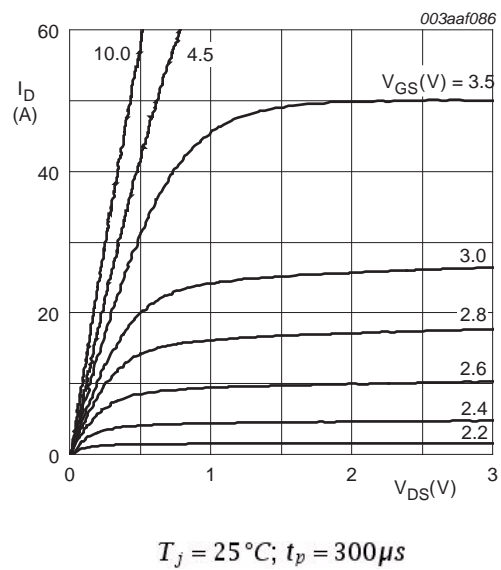
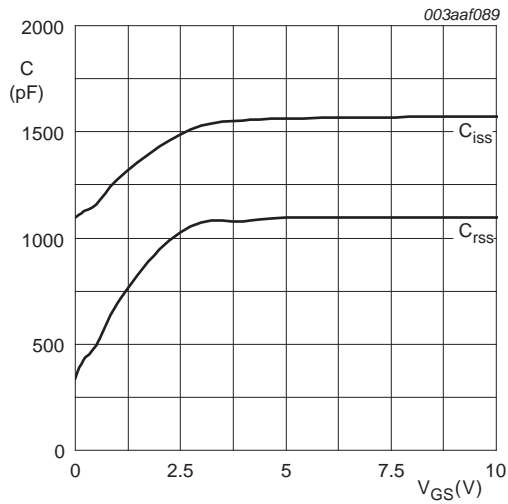
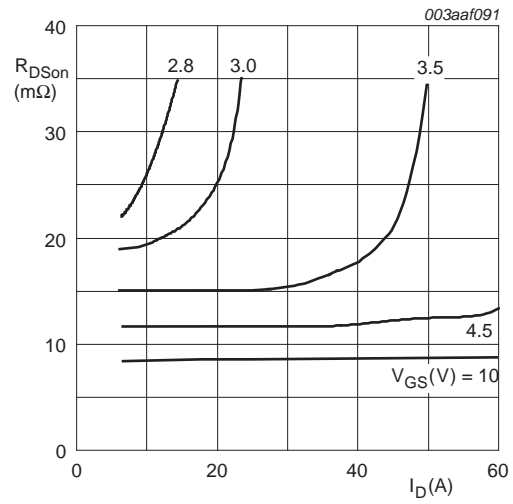


Fig 6. Output characteristics: drain current as a function of drain-source voltage; typical values



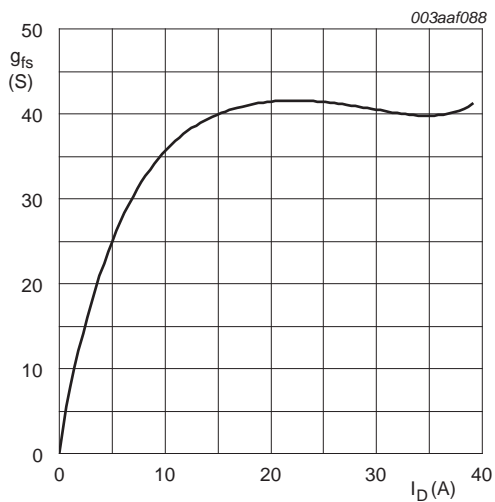
$V_{DS} = 0V; f = 1MHz$

Fig 7. Input and reverse transfer capacitances as a function of gate-source voltage; typical values



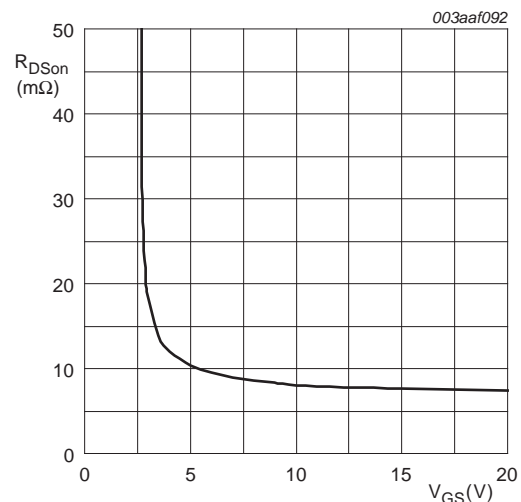
$T_j = 25^\circ C; t_p = 300\mu s$

Fig 8. Drain-source on-state resistance as a function of drain current; typical values



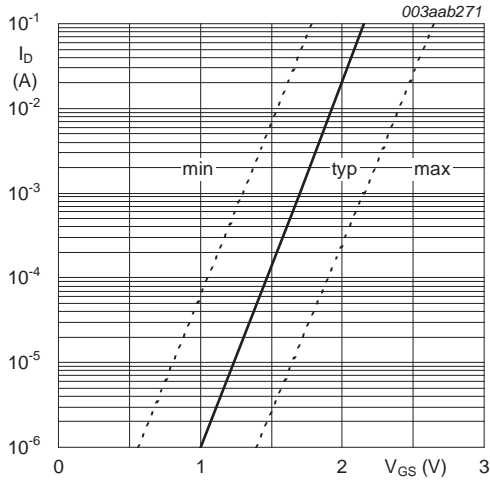
$T_j = 25^\circ C; V_{DS} = 10V$

Fig 9. Forward transconductance as a function of drain current; typical values



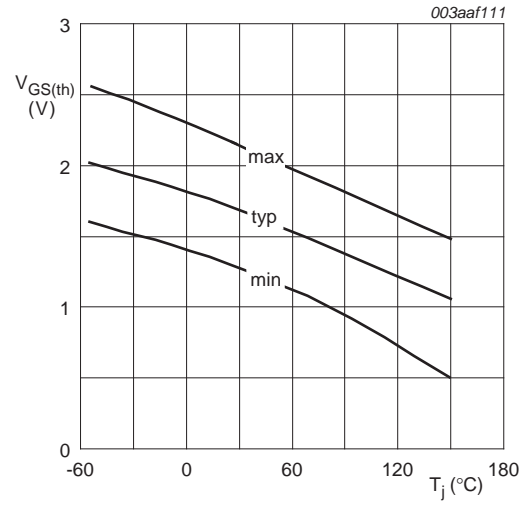
$T_j = 25^\circ C; I_D = 15A$

Fig 10. Drain-source on-state resistance as a function of gate-source voltage; typical values



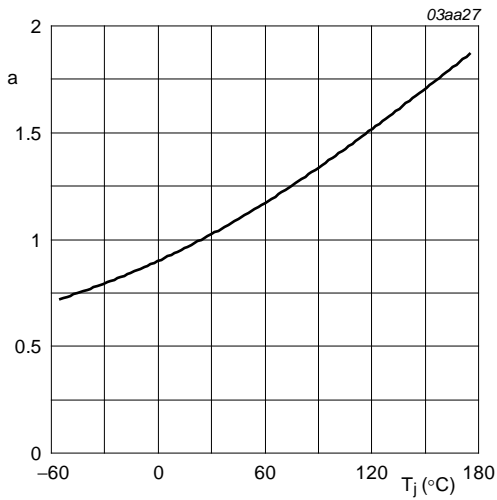
$T_j = 25^\circ\text{C}; V_{DS} = 5\text{V}$

Fig 11. Sub-threshold drain current as a function of gate-source voltage



$I_D = 1\text{mA}; V_{DS} = V_{GS}$

Fig 12. Gate-source threshold voltage as a function of junction temperature



$$a = \frac{R_{DSon}}{R_{DSon(25^\circ\text{C})}}$$

Fig 13. Normalized drain-source on-state resistance factor as a function of junction temperature

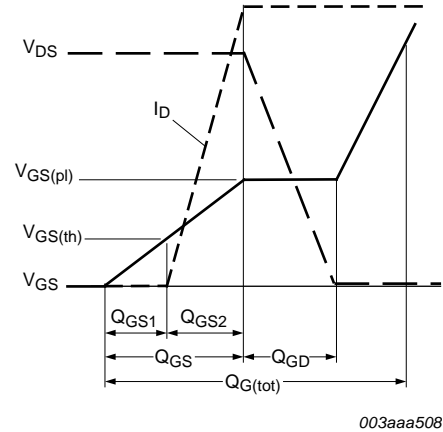
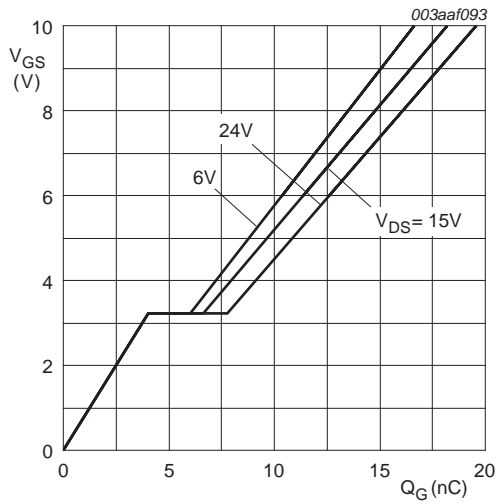
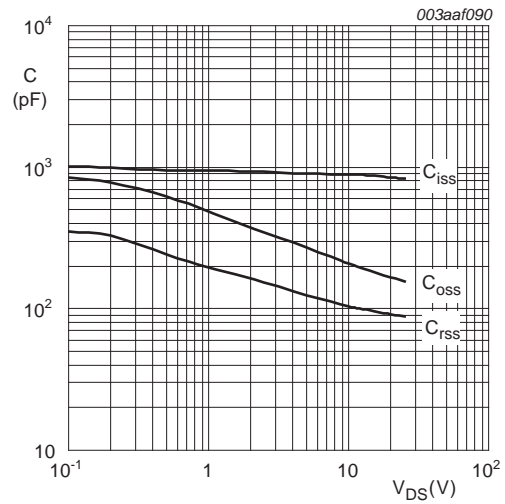


Fig 14. Gate charge waveform definitions



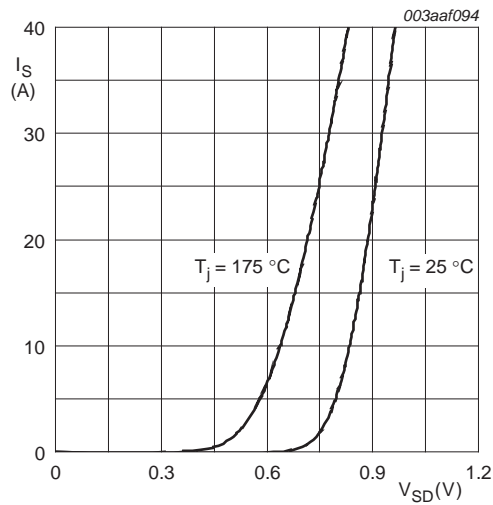
$T_j = 25\text{ }^\circ\text{C}; I_D = 10\text{ A}$

Fig 15. Gate-source voltage as a function of gate charge; typical values



$V_{GS} = 0\text{ V}; f = 1\text{ MHz}$

Fig 16. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$V_{GS} = 0\text{ V}$

Fig 17. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values

7. Package outline

Plastic single-ended surface-mounted package (LPAK); 4 leads

SOT669

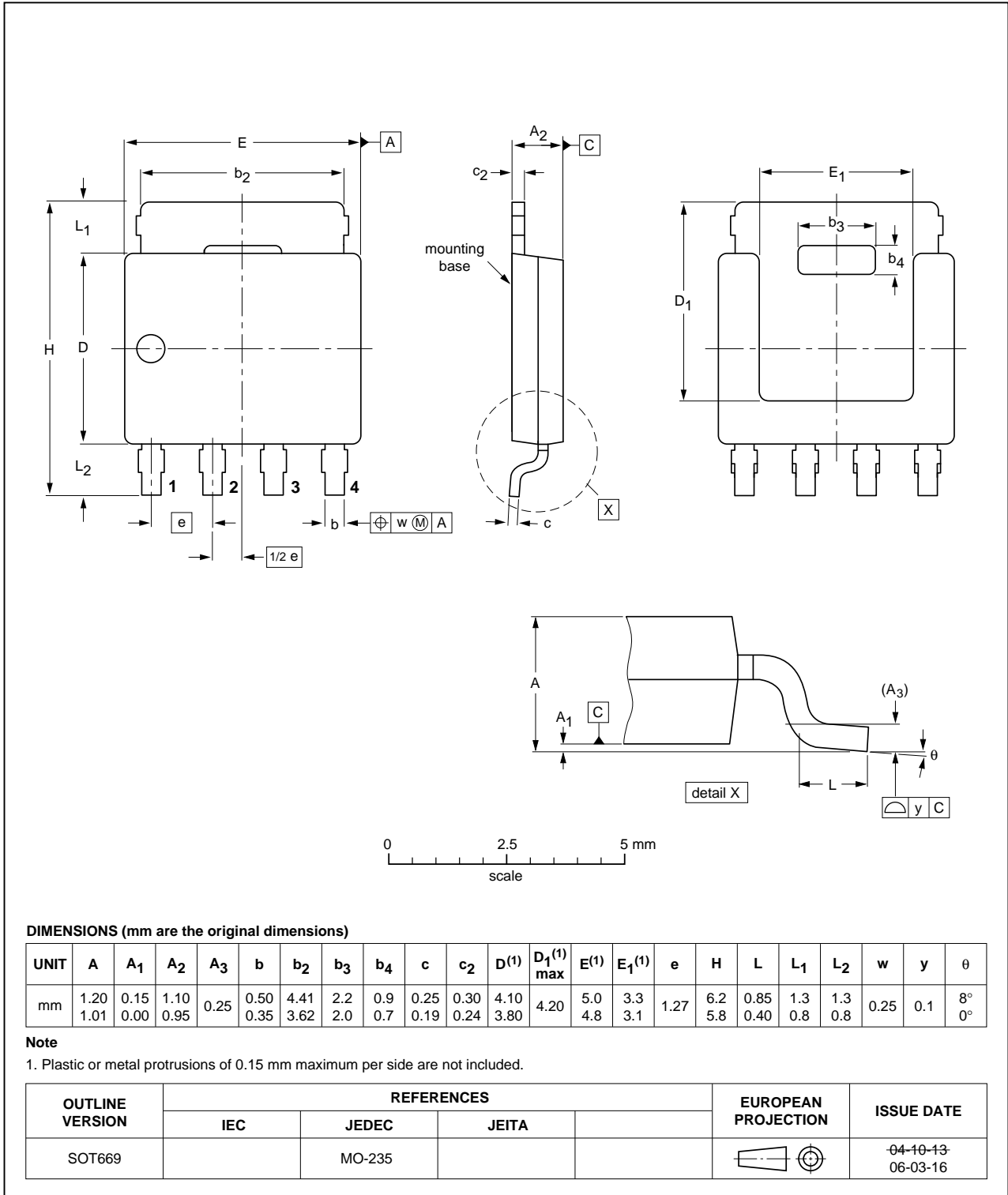


Fig 18. Package outline SOT669 (LPAK)

8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PH9130AL v.5	20110114	Product data sheet	-	PH9130AL v.4
Modifications:	<ul style="list-style-type: none">• Data sheet status changed from Preliminary to Product.• Various changes to content.			
PH9130AL v.4	20101119	Preliminary data sheet	-	PH9130AL v.3

9. Legal information

9.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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